

Description

The AP2300MI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 20V I_{D} = 3.3A$

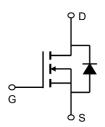
 $R_{DS(ON)}$ < 28m Ω @ V_{GS} =4.5V

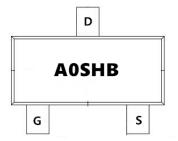
Application

Battery protection

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2300MI	SOT-23-3L	A0SHB	3000

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Parameter Rating	
VDS	Drain-Source Voltage	20	V
Vgs	Gate-Source Voltage	±12	V
ID@T _A =25°C	Continuous Drain Current, V _{GS} @ 4.5V ¹	3.3	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 4.5V ¹	2.8	А
IDM	Pulsed Drain Current ²	14.4	А
P _D @T _A =25°C	Total Power Dissipation ³	1	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
ReJA	Thermal Resistance Junction-ambient ¹ 125		°C/W
Rejc	Thermal Resistance Junction-Case ¹	80	°C/W



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20	22		V	
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =3A		23	32	mΩ	
T CDS(ON)	Static Brain Source Charles Stance	V _{GS} =2.5V , I _D =2A		29	35		
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	0.5	0.75	1.2	V	
Ipss	Daria Carras I askana Carras	V _{DS} =16V , V _{GS} =0V , T _J =25°C			1	- uA	
	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =55°C			5		
Igss	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =3A		10.5		S	
Qg	Total Gate Charge (4.5V)			4.6			
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =3A		0.7		nC	
Qgd	Gate-Drain Charge			1.5			
T _{d(on)}	Turn-On Delay Time			1.6			
Tr	Rise Time	V_{DD} =10V , V_{GS} =4.5V , R_G =3.3 Ω		42			
T _{d(off)}	Turn-Off Delay Time	I _D =3A		14		ns	
Tf	Fall Time			7			
Ciss	Input Capacitance			310			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		49		pF	
Crss	Reverse Transfer Capacitance			35			
ls	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			3.6	Α	
Vsp	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2 . The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$
- 3. The power dissipation is limited by 150°C junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

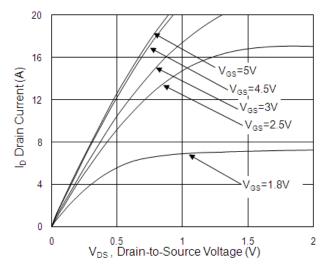


Fig.1 Typical Output Characteristics

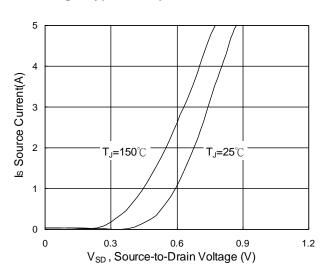


Fig.3 Source Drain Forward Characteristics

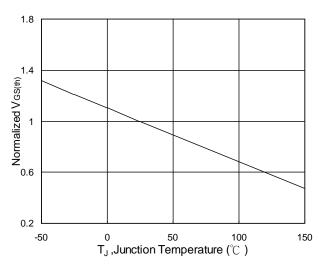


Fig.5 Normalized V_{GS(th)} vs. T_J

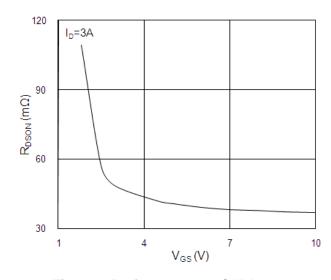


Fig.2 On-Resistance vs. G-S Voltage

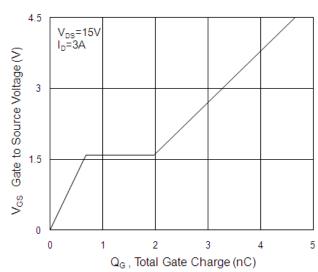


Fig.4 Gate-Charge Characteristics

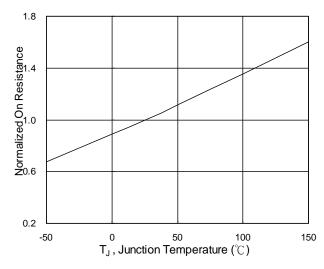
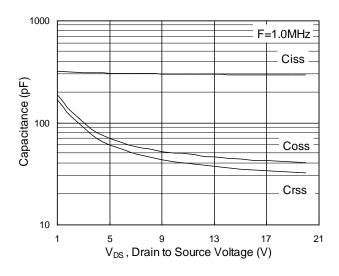


Fig.6 Normalized R_{DSON} vs. T_J







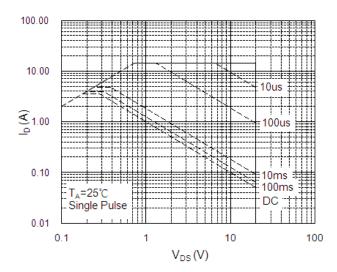


Fig.7 Capacitance

Fig.8 Safe Operating Area

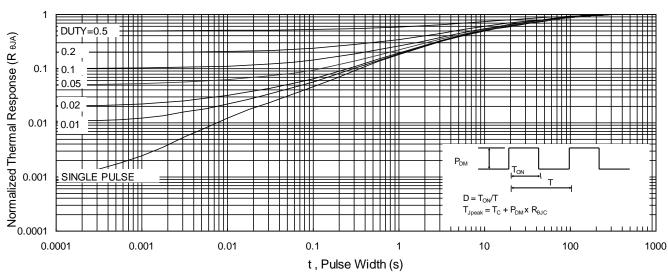
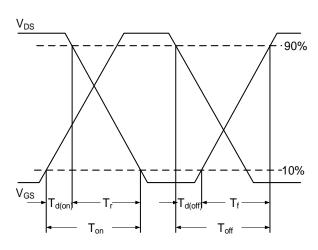


Fig.9 Normalized Maximum Transient Thermal Impedance





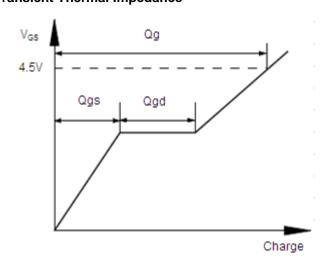
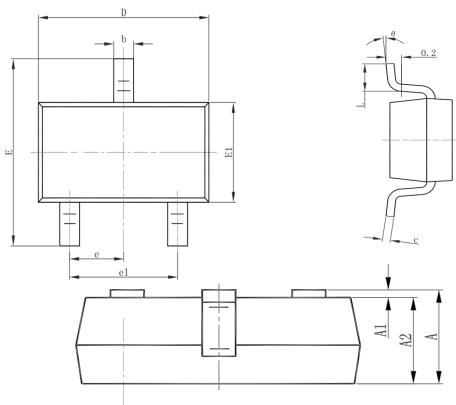


Fig.11 Gate Charge Waveform



Package Mechanical Data-SOT-23-3L



Complete al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.03	7(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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Edition	Date	Change
Rve1.0	2020/7/1	Initial release

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